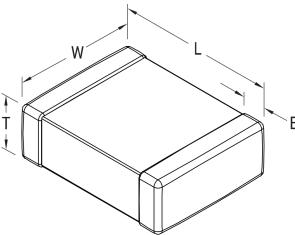


C1206C103F5GEC

ESD SMD Comm COG, Ceramic, 0.01 uF, 1%, 50 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206



Click here for the 3D model.

Dimensions		
Chip Size	1206	
L	3.2mm +/-0.2mm	
W	1.6mm +/-0.2mm	
Т	0.9mm +/-0.10mm	
В	0.5mm +/-0.25mm	

Packaging Specifications		
Packaging	Bulk, Bag	
Packaging Quantity	1	

General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	50 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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